

Interposers, Connectors and Interconnects

Board to Board, Device to Board, Device to Device



Applications

- *Semiconductor*
- *Military*
- *Aerospace*
- *Biomedical*
- *Telecom*
- *Automotive*



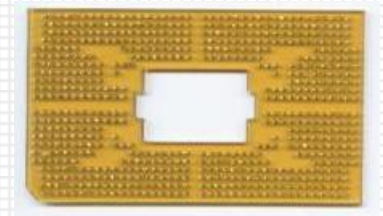
Features

- *Solderless*
- *Light Weight*
- *Low Profile*
- *Shock Resistant*
- *Extended Temps*
- *High Current*
- *High Frequency*



Advantages

- *Minimal Parasitics*
- *High Repeatability*
- *Cost Effective*
- *A Proven Approach*



Materials available: Ultem, Teflon, G10, PEEK, PPS, Torlon, Aluminum, Brass, others